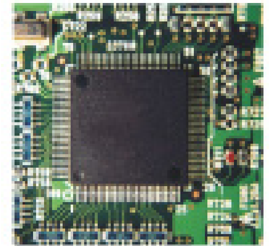
焊锡膏 Solder Paste

印刷用

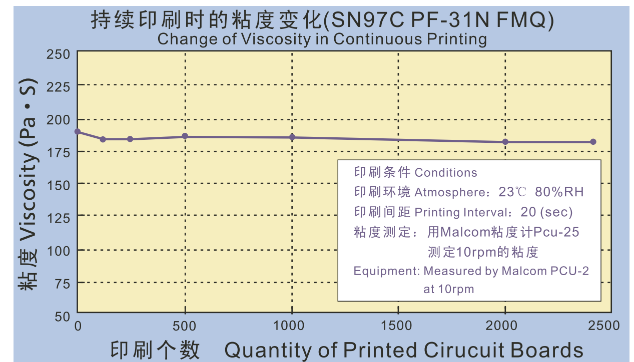
合金系列 Alloy system	编号 Product code	熔点(℃) Melting point	粒子范围(μm) Suitable • Feature	flux含有量 Flux content	粘度 Viscosity Pa • s	用途 • 特长 Suitable • Feature
Sn/Ag/Cu	SN96CI PF-33 FMQ	217	45-20	11.1	190	印刷性良好，能控制印刷时的粘度变化 Good printing performance. Stabilized viscosity is obtainable under continuous printing
	SN97C PF-31N FMQ	218-219		10.9	190	用于CSP与0.23ф对应 Suitable for CSP Stencil. Max size: 0.23 mm dia.
	SN97C PF-37 SFMQ		38-10	10.8	190	
Sn/Cu+Ni	SN100C PF-25 FMQ	227	45-20	10.7	185	印刷性良好，控制加热时的松弛 Good printing performance. Prevent dump formation when heated.
Sn/Ag/Cu/Bi	LF-C2 PF-39 FMQ	208-213		10.8	185	印刷性湿润性良好，控制加热时的松弛 Good printing performance & solderability. Prevent dump formation when heated.
Sn/Ag/In/Bi	LF-SA PF-5 FMQ	202-214		11.5	180	能够控制经时间变化而变少的锡球 Prevent the formation of solder ball. Stabilized viscosity
	SN88 PF-51 FMQ	198-210		11.5	180	控制经时间变化及加热时的松弛 Longer stickiness is obtainable under continuous printing. Prevent dump formation when heated
Sn/Ag	SN96 PF-36 AMQ	221	53-25	11.8	190	印刷性良好 Good printing performance
Sn/Sb	95A PF-35 AMQ	236-243		11.6	185	印刷性良好 Good printing performance
Sn/Zn	LF-Z1 PF-14 FMQ	199	45-20	12.0	160	适合大气中回流焊接，抑制锡球，粘度稳定 Reflow solderable in air atmosphere. Prevent the formation of solder ball. Stabilized viscosity.



100 Pin(0.5mm pitch)QFP reflow soldered with SN96CI

用于软钎焊

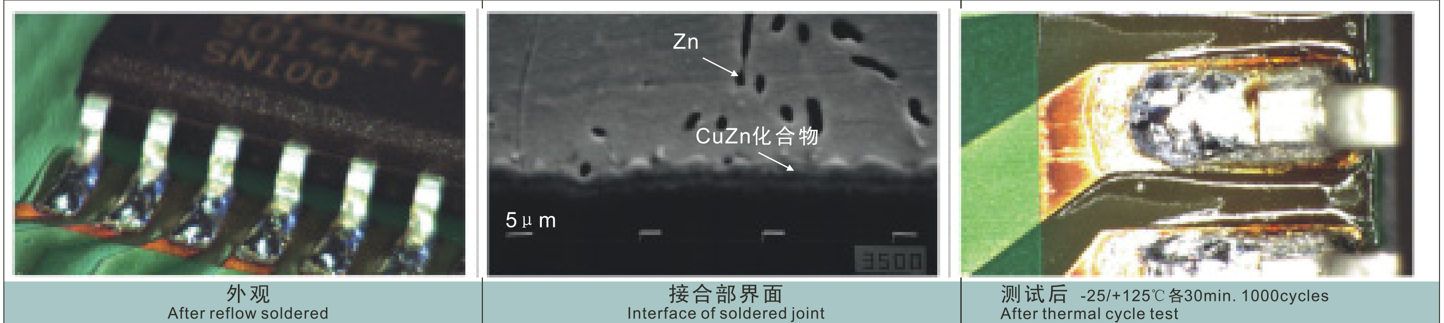
合金系列 Alloy system	编号 Product code	熔点(℃) Melting point	粒子范围(μm) Powder particle size	用途 • 特长 Suitable • Feature
Sn/Ag/Cu	SN96CI RMA FDQ M-21	217	45-20	适用于急速加热 Suitable for rapid heating
	SN96CI RMA FDQ H-1			吐出稳定性良好，适用于急速加热 Suitable dispensing. Suitable for rapid heating
	SN97C RMA FDQ M-21	218-219		适用于急速加热 Suitable for rapid heating
	SN97C RMA FDQ H-1			吐出稳定性良好，适用于急速加热 Suitable dispensing. Suitable for rapid heating
Sn/Cu+Ni	SN100C RMA FDQ H-1	227		
Sn/Ag	SN96 RMA FDQ H-1	221		



■ 回流焊 LF-Z1 PF-14 FMQ Reflow Soldering

残留物成膜，无裂痕
Crack-free at its residue

热循环试验后的板面无白色氧化物
No white oxide on the soldered board after thermal cycle test.



外观 After reflow soldered | 接合部界面 Interface of soldered joint | 测试后 -25/+125℃各30min. 1000cycles After thermal cycle test

■ 参考

最合适的回流焊温度曲线根据电路板及回流焊装置功能的不同而有所不同，请针对使用的产品及回流焊装置等，确认实际的温度曲线。

The optimum reflow profile is to some extent dependent on the characteristics of the board and the capability of the reflow oven. The thermal profile below has been found to work in the Nihon Superior laboratory and could be used a starting point in optimizing the profile for a particular board and oven.